



## 17<sup>th</sup> ESD-FORUM

November 30 – December 02, 2021  
Holiday Inn, Munich, Germany

### \*\*\* ANNOUNCEMENT and CALL FOR PAPERS \*\*\*

Subject of the conference are electrostatic effects (Electrostatic Discharge, ESD) and Electrical Overstress (EOS) on electronics, as well as problems related to electrostatic phenomena in other areas like for instance healthcare. The intention is to support the discussion between the industrial and scientific communities in order to improve possible solutions for ESD and EOS related problems for any application of electronic components.

**Submitted papers should cover the following fields:**

#### Fundamentals

- Electrostatic Charging (Mechanisms)
- Materials for ESD Control and Protection
- ESD and Latch-up (Real-World Events and Models)
- Secondary Effects (E-Fields, H-Fields, EMI, Latch-up)

#### Measurement

- Measurement of Electrostatic Charging and Fields
- Characterization of Protection Elements on Wafer-Level, Component-Level and System-Level
- Tests and Qualification on Component Level and System Level (Procedures, Equipment, Results)

#### ESD Control

- Precaution and Measures to prevent ESD and EOS (Packing, Handling, Shipment, Automated and Non-Automated Processes)
- ESD Control Programs (Contents, Implementation, Problems, Cost-Benefit Analysis)

#### Protection Elements on Component/System-Level

- ESD and Latch-up Protection Structures (discrete, integrated, for HV/RF-Applications, LEDs, MEMs, ...)
- ESD and Latch-up Protection Strategies (passive, active, Shielding, Filtering, Clamping, Single-/Multi-Stage)
- Modelling, Simulation and Software Verification of Structures, Components, Circuits and Systems

#### Damage

- EOS (Occurrence, Types, Root Causes)
- ESD-, EOS- and Latch-up Failures and Mechanisms (in the Field, in Production, on System/Component-Level)
- Reliability (Failure Mechanisms, Rates, Occurrence)
- Electrostatic problems in healthcare

#### Requirements

- ESD- and Latch-up Requirements of different Applications (Automotive, Consumer, Industry, Aerospace, Medical, Military, Communications)
- Standards (Field of Application, Application, Problems)

- Education and Training (ESD Professionals, Designers, Managers)

#### Conference Language

German or English language may be used for printed materials, presentation and discussion.

#### Proceedings

All accepted papers will be published in the "ESD-Forum" conference proceedings.

#### Submission Guidelines

Extended abstracts of 500 words should be sent by e-mail to:  
E-mail: [tilo.brodbeck@esdforum.de](mailto:tilo.brodbeck@esdforum.de)

#### Dead Lines

June 30, 2021	Submission of extended abstracts, approximately 500 words
July 30, 2021	Notification of the authors on acceptance of the papers
September 16, 2021	Submission of full papers

#### Award

The best paper will be awarded by the Technical Program Committee.

#### Chairman

Wolfgang Stadler (Intel Deutschland GmbH)

#### Chairman Technical Program Committee

Michael Graf (Robert Bosch GmbH)

#### Technical Program Committee

Members of the ESD FORUM e.V.

#### Exhibition

Parallel to the conference, it is planned to offer an exhibition in adjacent rooms. You can promote your products or place respective literature. Please contact the ESD FORUM e.V. for more information before September 30, 2021.

#### Presentations of Exhibitors

Exhibitors have the opportunity to introduce products, equipment and/or services in a short presentation.

#### Organization

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